



PATENT APPLICATION  
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Tadahiro KEGASAWA, et al.

Appln. No.: 10/071,183

Group Art Unit: 1733

Confirmation No.: 2983

Examiner: Not Yet Assigned

Filed: February 11, 2002

For: RESIN FILM FORMING METHOD, AND LAMINATE PRODUCTION METHOD AND APPARATUS

PRELIMINARY AMENDMENT

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Prior to examination, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Pages 1 and 2 ~~please~~ delete the paragraph that bridges these two pages and insert the following paragraph:

So far, as countermeasures against the above problems, there have been adopted a  
method for improving the material physical property by mixing a plurality of materials (Japanese Patent Publication Nos. 64-3655 and 5-82806), a method of changing the flow of a resin in the extruder die (Japanese Patent Publication No. 6-61819 and Japanese Patent Application Publication No. 64-64822) and a method of cooling both ends of the resin film extruded from an extruder die (Japanese Patent Publication No. 5-33134).

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